

# **Holt Integrated Circuits**

23351 Madero Mission Viejo, CA 92691

# **PRODUCT CHANGE NOTIFICATION (PCN)**

PCN INFORMATION								
PCN # Title	0707 Qualification of "QFP" Package at CEI, Thailand Assembly Location for HI-8448PQxx-xx		Date:		03/06/08			
THIO			Date Effective:		09/01/07			
Contact:	Scott Paladichuk			Title:		Director of Quality		
Phone #:	949-859-8800							
Fax #:	949-859-9643		Attachment:		Yes			
E-mail:	spaladichuk@holtic.com			Samples:		Available		
MEANS OF DISTINGUISHING CHANGED DEVICES								
	Product Mark		Back Mark		$\square$	Date Code		Other
ALL HI-8488PQxx-xx Product Listed with Date Code <u>&gt; 0727</u>								
CHANGE TYPE								
	Design		Electrical Specification		$\boxtimes$	Mechanical Specific	ation	
	Wafer Fab Site		Wafer Fab Material			Wafer Fab Process		
$\boxtimes$	Assembly Site	$\boxtimes$	Assembly Material		$\boxtimes$	Assembly Process		
	Test Site		Test Process			Packing/Shipping/La	abeling	
	Other:							

DETAILS

### **DESCRIPTION OF CHANGE:**

Initiate the assembly builds of Holt Product HI-8488PQxx-xx at CEI Thailand assembly location. Product planned to be assembled at CEI is the 44 L QFP package configuration.

#### **REASON FOR CHANGE:**

To qualify CEI Thailand as sub-contract source for this package type which will enable Holt to maintain the necessary capacity and supply for HI-8488PQxx-xx product.

### PRODUCT AFFECTED:

8448PQI	Date Code >0727	8448PQI-10	Date Code >0727
8448PQT	Date Code <u>&gt;0727</u>	8448PQT-10	Date Code >0727
8448PQIF	Date Code >0727	8448PQIF-10	Date Code >0727
8448PQTF	Date Code <u>&gt;0727</u>	8448PQTF-10	Date Code <u>&gt;</u> 0727

#### **RELIABLITY/QUALIFICATION SUMMARY:**

There is no negative impact to fit, form, functionality or reliability due this change. No changes to customer assembly processes are needed, provided customers follow Holt recommended soldering processes and comply with the Moisture Sensitivity information indicated on the label.

Tests were conducted on assembled product that is representative of planned Holt product build.

Please see Attachment 1 for Reliability details and qualification plan.

**Customer Acknowledgement of Receipt of PCN** 

Holt records indicate that you require written notification of this change. Please acknowledge below or e-mail to grant approval or request additional information. If Holt does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

Holt reserves the right to ship either version manufactured after the process change effective date until the inventory on the prior version has been depleted.

Customer Signature/Date	Approval for shipments prior to effective date
HOLT ACKNOWLEDGEMENT OF RECEIPT:	
RECEIVED BY:	Date



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# **PRODUCT CHANGE NOTIFICATION (PCN)**

	ATTACHMENT I INFORMATION – PCN 0706
PCN Type:	Assembly Process
Title	Qualification of "QFP" Package at CEI, Thailand Assembly Location for HI-8448PQxx-xx
Data Sheet Change:	Yes – Package Dimensions DS8444 Rev. F was released 2/08
Detail of Change	To qualify CEI Thailand as sub-contract source for this package type which will enable Holt to maintain the necessary capacity and supply for HI-8488PQxx-xx product . Details of package drawing included in DS8444 Rev. F.
Product	Table 1

Qualification Information

Package: QFP 10x10 – 44 leads	Mold Compound: EME-6600CGL
Dimension: 10x10x1.4mm	Die Attach: Ablebond 84-1LMISR4
Assembly Site: CEI Thailand	Leadframe: Cu
	Wire: Gold wire, 1.25mil

### See Attachment II

## Reliability Report HI-8448PQxx-xx QR-8009 Rev. 1.0

Detail of Reliability Qualification Plan The following indicates the testing completed to cover this assembly change. A detailed list of the qualifications tests performed and the results are supplied in this notice.

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Schedule: Start: August 2007 End: January 2008 Qualification Plan: Test Results:

See Attachment II

Reliability Report HI-8448PQxx-xx QR-8009 Rev. 1.0